



# **Product Disassembly Instructions**

**Product Category:** 

**Panel PC** 

**Product Marketing Name / Model:** 

PPC-324W-P7

**Purpose:** The document provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC and 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

| Item Description   | Notes   | Quantity of items included in product |
|--|---|---------------------------------------|
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)                         | With a surface greater than 10 sq. cm Mother<br>board, Card Reader board, USB Daughter<br>board, LID Daughter board               | 8                                     |
| Batteries  | All types including standard alkaline and lithium coin or button style batteries 6cell battery or 9 cell battery, and RTC battery | 1                                     |
| External electrical cables and Power cord  |   | 0                                     |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm                      | Includes background illuminated displays with gas discharge lamps   | 1                                     |
| Cathode Ray Tubes (CRT)  |   | 0                                     |
| Gas Discharge Lamps  |   | 0                                     |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height |   | 0                                     |

| Item Description                         | Notes   | Quantity of items included in product |
|--|---|---------------------------------------|
| Mercury-containing components            | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | 0                                     |
| Capacitors / condensers (Containing PCB) |   | 0                                     |



| Plastics containing Brominated Flame Retardants weighing > 25 grams                                      | (Not including PCBs or PCAs already listed as a separate item above)             | 0 |
|--|--|---|
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner     | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0 |
| Asbestos waste and components which contain asbestos   |  | 0 |
| Components containing refractory ceramic fibers  |  | 0 |
| Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons(HFC), hydrocarbons (HC) |  | 0 |
| Components, parts and materials containing radioactive substances  |  | 0 |



## 2.0 Disassembly Tool

List the tools that would typically be used to disassemble the product to a point where components and materials can be removed.

| Disassembly Tool | Picture |
|------------------|---------|
| Screwdriver      | 0       |
| Lever            |         |
| Star Screwdriver | 0       |
| Hexagon Driver   | 0       |
| Slanted pliers   |         |
| Pliers           |         |
| Hammer           | 8-      |
| Knife            |         |



### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials.

#### A. Disassembly Box module.

- A-1. Disassembly 10 pcs screw to remove the MB cover.
- A -2. Disassembly 2pcs antenna rubber cap from MB cover.
- A -3. Disassembly 4 pcs screw to separate the HDD/SSD and HDD/SSD bracket.
- A -4. Disassembly 4 pcs screw to remove the HDD/SSD tray from middle cover.
- A -5. Disassembly 2 pcs screw to remove the antenna bracket from middle cover.
- A -6. Disassembly DDR module from DDR socket.
- A -7. Disassembly mSATA card(2pcs screw) and Mini PCle card(2pcs screw) from each socket.
- A -8. Remove RTC battery wire cable.
- A -9. Disassembly Hex 4pcs from COM port, screw 7pcs from mother board to separate the mother board and chassis.
- A-10. Disassembly 4pcs screw to remove IO Bracket.
- A-11. Disassembly 2 pcs screw to remove Internal USB mode.
- A-12. Disassembly 2 pcs screw to remove Internal USB from Internal USB mode.

#### **B.** Disassembly Panel module.

- B-1. Disassembly screw 14pcs to remove the middle cover.
- B-2. Disassembly screw 4pcs to remove the Speaker module.
- B-3. Disassembly screw 3pcs to remove the Touch control board.
- B-4. Disassembly 2pcs to separate the LED driver board.
- B-5. Disassembly screw 11pcs to remove LCD mode from Front Bezel.
- B-6. Disassembly screw 4pcs to separate the LCD bracket left and right with LCD module.
- B-7. Separate the LCD sponge from LCD opening bezel.
- B-8. Disassembly screw 1pcs to remove the LED indicator board.
- B-9. Remove the waterproof from front bezel.



3.2 Exploded view drawing. Insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

